



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	IPD068N10N3 G	<b>Issued</b>	11. May 2021
<b>MA#</b>	MA001662036		
<b>Package</b>	PG-TO252-3-313	<b>Weight*</b>	321.79 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.560	1.73	1.73	17280	17280
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		137	
	non noble metal	iron	7439-89-6	0.147	0.05		458	
	non noble metal	copper	7440-50-8	147.096	45.72	45.78	457126	457721
wire	non noble metal	aluminium	7429-90-5	5.096	1.58	1.58	15837	15837
encapsulation	inorganic material	zinc oxide	1314-13-2	1.352	0.42		4200	
	miscellaneous	miscellaneous	-	6.758	2.10		21001	
	plastics	epoxy resin	-	20.273	6.30		63002	
	inorganic material	silicon dioxide	60676-86-0	106.772	33.18	42.00	331810	420013
lead finish	non noble metal	tin	7440-31-5	3.740	1.16	1.16	11623	11623
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4414	4425
solder	non noble metal	tin	7440-31-5	0.086	0.03		269	
	noble metal	silver	7440-22-4	0.108	0.03		336	
	non noble metal	lead	7439-92-1	4.126	1.28	1.34	12821	13426
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	5.96	5.97	59597	59675
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com